
UNITED STATES
SECURITIES AND EXCHANGE COMMISSION
Washington, D.C. 20549

FORM 8-K

CURRENT REPORT

Pursuant to Section 13 or 15(d) of the Securities Exchange Act of 1934

Date of Report (Date of Earliest Event Reported): April 22, 2015

PDF SOLUTIONS, INC.

(Exact name of registrant as specified in its charter)

000-31311

(Commission File Number)

Delaware
(State or Other Jurisdiction of Incorporation)

25-1701361
(I.R.S. Employer Identification No.)

333 West San Carlos Street, Suite 1000
San Jose, CA 95110

(Address of principal executive offices, with zip code)

(408) 280-7900

(Registrant's telephone number, including area code)

Check the appropriate box below if the Form 8-K filing is intended to simultaneously satisfy the filing obligation of the registrant under any of the following provisions:

- Written communications pursuant to Rule 425 under the Securities Act (17 CFR 230.425)
 - Soliciting material pursuant to Rule 14a-12 under the Exchange Act (17 CFR 240.14a-12)
 - Pre-commencement communications pursuant to Rule 14d-2(b) under the Exchange Act (17 CFR 240.14d-2(b))
 - Pre-commencement communications pursuant to Rule 13e-4(c) under the Exchange Act (17 CFR 240.13e-4(c))
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TABLE OF CONTENTS

Item 7.01. Regulation FD Disclosure
Item 9.01. Financial Statements and Exhibits
SIGNATURES
EXHIBIT INDEX

Item 7.01. Regulation FD Disclosure.

On April 22, 2015 , PDF Solutions (the “Company”) issued a press release regarding the release of Exensio™-Test software for semiconductor companies. A copy of the press release is attached hereto as Exhibit 99.1.

The information in this Item 7.01, including Exhibit 99.1, is being furnished and shall not be deemed “filed” for purposes of Section 18 of the Securities Exchange Act of 1934, as amended (the “Exchange Act”), or otherwise subject to the liabilities under that Section, and shall not be deemed incorporated by reference into any filing of the Company under the Securities Act of 1933, as amended, or the Exchange Act, except as shall be expressly set forth by specific reference in such filing.

Item 9.01. Financial Statements and Exhibits.

(d) Exhibits

Exhibit No.	Description
99.1	Press Release dated April 22, 2015 regarding announcement of Exensio™- Test software.

SIGNATURES

Pursuant to the requirements of the Securities Exchange Act of 1934, the Registrant has duly caused this report to be signed on its behalf by the undersigned hereunto duly authorized.

PDF SOLUTIONS, INC.
(Registrant)

By: /s/ Gregory C Walker
Gregory C Walker
VP, Finance, and Chief Financial Officer
(Principal Financial Officer)

Dated: April 22, 2015

EXHIBIT INDEX

Exhibit No.

Description

99.1

Press Release dated April 22, 2015 regarding announcement of Exensio™- Test software.

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PDF Solutions Announces the Release of Exensio™-Test Augmenting Its Big Data Solution for IC Manufacturing

Test Module for Exensio™ Platform Enables IDM and Fabless Customers to Better Manage, Control and Optimize Test Operations and Productivity

San Jose, Ca. (April 22, 2015) - The leading provider of yield improvement technologies and services for the integrated circuit (IC) process life cycle announced today the release of Exensio™-Test software for semiconductor companies. PDF Solutions is well known for its expertise in process equipment control with the Exensio Platform, comprising the Exensio™-Yield and Exensio™-Control modules for yield improvement as well as fault detection and classification. Based on customer feedback, PDF Solutions has now expanded the platform to address critical areas of test, packaging and assembly with its new Exensio-Test offering. This module combines technology gained through the acquisition of key semiconductor software assets from Salland Engineering entities with the Big Data capabilities of PDF's Exensio Platform. This new module provides test floor operation, adaptive test and analysis technology that produces diagnostic and predictive information during test, assembly and packaging operations. This information is critical to optimizing customers' test operations, productivity and yields.

Exensio-Test, now deployed and available worldwide, enables semiconductor manufacturers to improve the efficiency and quality of their testing, as well as experience these additional benefits:

- Significantly reduced test times through the implementation of real-time adaptive test algorithms. This reduction is required for advanced products and processes with stringent PPM (parts-per-million) defectivity requirements.
 - Reduced test time through optimization of test probe setup selection and simultaneous tester/prober recipe optimization.
 - Increased test productivity and insight into test floor efficiency across a variety of subcontractor and in-house test facilities with real-time alarms and actions.
 - Linking of manufacturing data to root causes seen in wafer sort and final test, through utilization of advanced analysis, data mining and modeling features, as well as implementation of predictive alarms.
 - Co-optimization of overall equipment effectiveness (OEE), UPM, productivity and yield, when paired with PDF Solutions' scribe CV® technologies. This enables customers to optimize adaptive test.
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As part of the development of Exensio-Test, PDF Solutions acquired key semiconductor software assets from Salland Engineering entities. Salland Engineering's solutions were successfully implemented for test, packaging and assembly management on a worldwide basis. As part of the asset purchase, PDF Solutions acquired the following products from Salland: SE Probe and related modules, Optimizer, MapWarehouse (MWH), SE Dana, Quest, Skeleton, CM-FT, CCT, SwiftTest, TestScape, and TestVision. PDF Solutions continues to license and support these products as acquired from Salland, and will further develop and integrate them into the Exensio-Test module. PDF Solutions has already secured multi-year license and support agreements with many of Salland's former customers for the continued use of these products.

"We're happy to see that PDF has acquired these assets of Salland and excited to see integration of Salland's testing technology to round out the Exensio platform and provide a seamless link between our manufacturing data and the data we see at our subcontractors and test facilities," said Bob Lima, Director of Assembly and Test Operations at Peregrine Semiconductor. "We look forward to leveraging the entire Exensio platform with the Exensio-Yield and Exensio-Control modules, to optimize our chip yields and realize its direct positive impact on our profitability."

"PDF Solutions is currently providing customers unified access to process tool-level control, yield, and characterization data through our integrated FDC and YMS capabilities in Exensio," said Said Akar, General Manager at PDF Solutions. "However, we also want to provide state-of-the art testing at the production level. Now with the Salland technology we acquired, our fabless and IDM customers can leverage this information to significantly improve their test productivity, reach higher production yields, lower PPM and achieve a faster time-to-market."

Exensio-Test increases OEE of test cells through optimization of tester configurations, management of tester data, implementation of adaptive test algorithms, as well as other test floor management operations. This high level of testing is critical in many of today's electronics products which have stringent PPM defectivity requirements. Exensio-Test also has advanced adaptive test capabilities and is able to simultaneously maximize OEE and UPM (units tested per hour).

Forward-Looking Statements

The statements in this press release regarding the expected performance and capabilities of PDF Solutions products and services and the statements regarding continued adoption by customers are forward looking and are subject to events and circumstances of the future. Actual results could differ materially from those expressed in these forward-looking statements. Risks and uncertainties that could cause results to differ materially include risks associated with continued development, support, and market acceptance, and other risks set forth in PDF Solutions' periodic public filings with the Securities and Exchange Commission, including, without limitation, its Annual Report on Form 10-K, most recently filed on March 3, 2015, for the year ended December 31, 2014, other Annual Reports on Form 10-K, Quarterly Reports on Form 10-Q, most recently filed for the quarter ended September 30, 2014, and Current Reports on Form 8-K and amendments to such reports. The forward-looking statements made in this press release are made as of the date hereof, and PDF Solutions does not assume any obligation to update such statements or the reasons why actual results could differ materially from those projected in such statements.

About PDF Solutions

PDF Solutions, Inc. (NASDAQ: PDFS) is the leading provider of yield improvement technologies and services for the IC manufacturing process life cycle. PDF Solutions offers solutions that are designed to enable clients to lower costs of IC design and manufacture, enhance time to market, and improve profitability by addressing design and manufacturing interactions from product design to initial process ramps to mature manufacturing operations. PDF Solutions' Characterization Vehicle[®] (CV[®]) electrical test chip infrastructure provides the core modeling capabilities, and is used by more leading manufacturers than any other test chips in the industry. Proprietary Template[™] layout patterns provide optimum area, performance, and manufacturability for designing IC products. Exensio[™]-Yield provides world-class variability control in manufacturing by leveraging PDF Solutions' industry-leading yield management technology and fault detection and classification (FDC) with Exensio[™]-Control software. Exensio[™]-Test leverages integration and analysis technology that produces diagnostic and predictive information that can be used to further optimize semiconductor yields. Headquartered in San Jose, Calif., PDF Solutions operates worldwide with additional offices in Canada, China, France, Germany, Italy, Japan, Korea, and Taiwan. For the Company's latest news and information, visit <http://www.pdf.com/>.

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